ABSTRACT OF THE DISCLOSURE

A method of producing a circuit-parts sheet having a structure in which a light-nontransmitting circuit-forming pattern is secured in a photo-cured ceramic sheet and is exposed on both surfaces of said photo-cured ceramic sheet, comprising the steps of:
(a) forming the light-nontransmitting conductor pattern on the surface of a light-transmitting film;
(b) forming a photo-curable ceramic coating layer by applying a photo-curable slurry onto the surface of the film on which said conductor pattern is formed;
(c) forming a photo-cured ceramic sheet by photo-curing said photo-curable ceramic coating layer by the irradiation with light from the back surface of said film;
(d) removing uncured portions of said photo-curable ceramic coating layer by using a developing solution; and
(e) peeling off said carrier film.
Use of this circuit-parts sheet makes it possible to produce a multi-layer circuit board simultaneously satisfying both the requirement for decreasing the thickness of the insulating layers and the requirement of increasing the thickness of the wiring conductor layers.